Promoting Flexible Electronics

FlexTech is a SEMI Technology Community focused on the growth and success of the manufacturing and R&D ecosystem for flexible electronics (FE).

SEMI-FlexTech members enjoy special insights into the unique research and development funding program, connections with the fast-moving ecosystem of suppliers and customers, and exclusive SEMI member benefits.

ABOUT SEMI-FLEXTECH

For over 25 years, SEMI-FlexTech has been gathering industry, academia, the U.S. Government and not-for-profits, together in pursuit of a 3-part mission: Connect, Champion and Advocate for FE technology.

Flexible electronics (FE) are building blocks for products which are flexible, lightweight, low-power and contain sensors, power, and communications capability. Leveraging SEMI’s global footprint and membership base, SEMI-FlexTech is extending its reach and engaging with more organizations on the promise of FE products.

R&D PROGRAM

FlexTech’s R&D programs are unique examples of public/private partnerships. The U.S. Department of Defense has granted FlexTech multiple contracts to fund cooperative technology development in the area of flexible, printed and hybrid electronics.

The three programs under SEMI-FlexTech management include FlexTech, Nano-Bio Manufacturing Consortium (NBMC), and NextFlex, America’s Flexible Hybrid Electronics Manufacturing Institute, which operates as a semi-autonomous organization.

BENEFITS OF MEMBERSHIP

COMMUNITY: Join with other companies in supporting the manufacturing of flexible hybrid electronics.

LEVERAGE: Propose R&D projects to augment your company’s internal resources.

KNOWLEDGE: Engage in multiple forums with subject matter experts to assess technical trends and to obtain information to build your business development strategies.

PARTNERSHIPS: Identify and source global partners for potential collaboration through the SEMI network.

INFLUENCE: Participate in industry standards and technology road mapping activities.

SEMI-FLEXTECH FUNDING PROGRAMS

BECOME PART OF OUR COMMUNITY!
SEMI-FlexTech: A Global Gateway

CONFERENCES, EXHIBITIONS AND FORUMS
SEMI-FlexTech organizes regular gatherings of the flexible and printed electronics community in major electronics manufacturing and design markets. Successful FLEX Conferences are hosted around the world and serve to connect organizations, companies and academicians active in flexible and printed electronics. Presentations and networking at these events lead to greater collaboration and accelerate the development and adoption of the technology to a wider variety of applications.

FIND AN EVENT NEAR YOU AT WWW.SEMI.ORG/EVENTS

INTERNATIONAL STANDARDS DEVELOPMENT
Standards fall into several general categories, including:

- Metrics
- Materials
- Terms & Definitions
- Thin/Amorphous Silicon
- Test & Reliability

SEMI-FlexTech-NextFlex have joined forces with other standards-setting organizations (E.g. IPC) to plan for comprehensive coverage of standards for the sector, and decrease duplication. NextFlex also has a working group focused on gap analysis for standards for flexible electronics manufacturing.

BECOME PART OF OUR COMMUNITY!
FlexTech is a SEMI Technology Community and is open to any SEMI member in good standing, worldwide.

If your organization is already a member of SEMI, simply request inclusion in SEMI-FlexTech communications and activities by calling your local SEMI membership office.

If your organization is not a member of SEMI, join now and request membership in SEMI-FlexTech.

Membership in the SEMI-FlexTech Technical Council and Governing Council has special requirements. Contact us for more information.

EXISTING STANDARDS APPLICABLE TO FLEXIBLE ELECTRONICS
SEMI has over 1000 industry-developed and adopted standards which can be utilized for flexible electronics with little or no modification, including:

- SAFETY: guidelines on equipment safety, risk assessment and energy conservation
- MANUFACTURING EQUIPMENT PROTOCOLS: data acquisition, EDA, flowshop
- DISPLAY: films & substrates, metrology, properties
- SILICON: materials, test methods, terminology
- 3D & MEMS: thickness variation, warp/sori, flatness
- PHYSICAL INTERFACES: in-fab transport

FOR MORE INFORMATION
Contact us today to learn more about the flexible, printed and hybrid electronics community at SEMI

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